

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Cancelled)
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Currently amended) ~~The method of claim 1~~ A method for manufacturing a multilayer ceramic electronic component, comprising the steps of:  
preparing an unsintered multilayer ceramic body including stacked ceramic layers and internal electrodes, the internal electrodes being made mainly of a base metal;  
removing organic materials from the unsintered multilayer ceramic body to

provide a binder-removed multilayer ceramic body; and

sintering the binder-removed multilayer ceramic body under a reductive atmosphere,

wherein the amount of the organic materials remaining in the binder-removed multilayer ceramic body ranges from about 0.5 weight% to about 8.5 weight% of the binder-removed multilayer ceramic body, and wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of the organic materials from the ceramic layers in order to remove the organic materials uniformly throughout the unsintered multilayer ceramic body.

10. (Original) The method of claim 9, wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of the organic materials from the ceramic layers by more than about 5°C.

11. (Original) The method of claim 10, wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of the organic materials from the ceramic layers by more than about 10°C.

12. (Cancelled)

13. (Currently amended) ~~The method of claim 1~~ A method for manufacturing a multilayer ceramic electronic component, comprising the steps of:

preparing an unsintered multilayer ceramic body including stacked ceramic layers and internal electrodes, the internal electrodes being made mainly of a base metal;

removing organic materials from the unsintered multilayer ceramic body to provide a binder-removed multilayer ceramic body; and

sintering the binder-removed multilayer ceramic body under a reductive

atmosphere.

wherein the amount of the organic materials remaining in the binder-removed multilayer ceramic body ranges from about 0.5 weight% to about 8.5 weight% of the binder-removed multilayer ceramic body, and wherein the removing step includes the steps of increasing a pressure in a binder removing furnace up to a peak pressure, increasing a temperature in the binder removing furnace up to a peak temperature, decreasing the pressure when the temperature reaches a pressure-decreasing temperature, which is lower than the peak temperature, and maintaining the peak temperature for a predetermined of period.

14. (Original) The method of claim 13, wherein the peak pressure is about 10 atmospheres.

15. (Original) The method of claim 13, wherein the pressure-decreasing temperature is about 200°C and the peak temperature is about 300°C.

16. (Cancelled)